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Semiconductor Device, Its Fabrication Method and Electronic Device

Abstract of the Disclosure

A semiconductor device comprises: a semiconductor chip having a circuit fabrication surface and an electrode; a resin for covering the circuit fabrication surface of the semiconductor chip; and a resin film for covering a rear surface facing the circuit fabrication surface of the semiconductor chip. With the configuration described above, a crack can be prevented from being generated in the semiconductor chip.

Figure 2





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